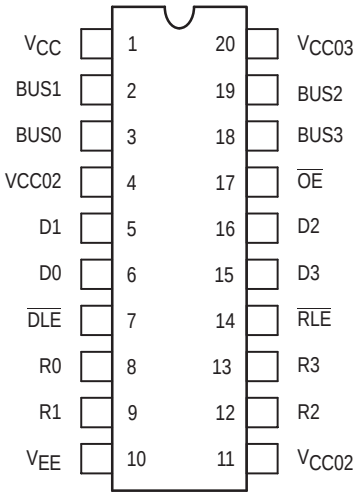
MC10H334

Quad Bus Driver/Receiver with Transmit and Receiver Latches

The MC10H334 is a Quad Bus Driver/Receiver with transmit and receiver latches. When disabled, ($\overline{OE}$ = high) the bus outputs will fall to –2.0 V. Data to be transmitted or received is passed through its respective latch when the respective latch enable ($\overline{DLE}$ and $\overline{RLE}$) is at a low level. Information is latched on the positive transition of $\overline{DLE}$ and $\overline{RLE}$. The parameters specified are with 25 Ω loading on the bus drivers and 50 Ω loads on the receivers.

- Propagation Delay, 1.6 ns Typical Data–to–Output
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K–Compatible

DIP & PLCC PIN ASSIGNMENT



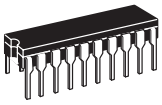
Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

NOTE:
Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Receiver outputs are terminated through a 50–ohm resistor to –2.0 volts dc. Bus outputs are terminated through a 25–ohm resistor to –2.0 volts dc.

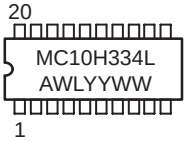
ON Semiconductor

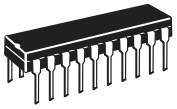
http://onsemi.com

MARKING DIAGRAMS

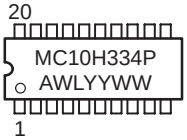


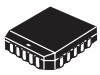
CDIP–20
L SUFFIX
CASE 732



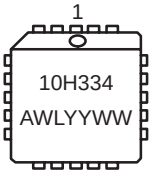


PDIP–20
P SUFFIX
CASE 738





PLCC–20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H334L	CDIP–20	18 Units/Rail
MC10H334P	PDIP–20	18 Units/Rail
MC10H334FN	PLCC–20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply (V_{CC} = 0)	–8.0 to 0	Vdc
V_I	Input Voltage (V_{CC} = 0)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	–55 to +150 –55 to +165	°C °C

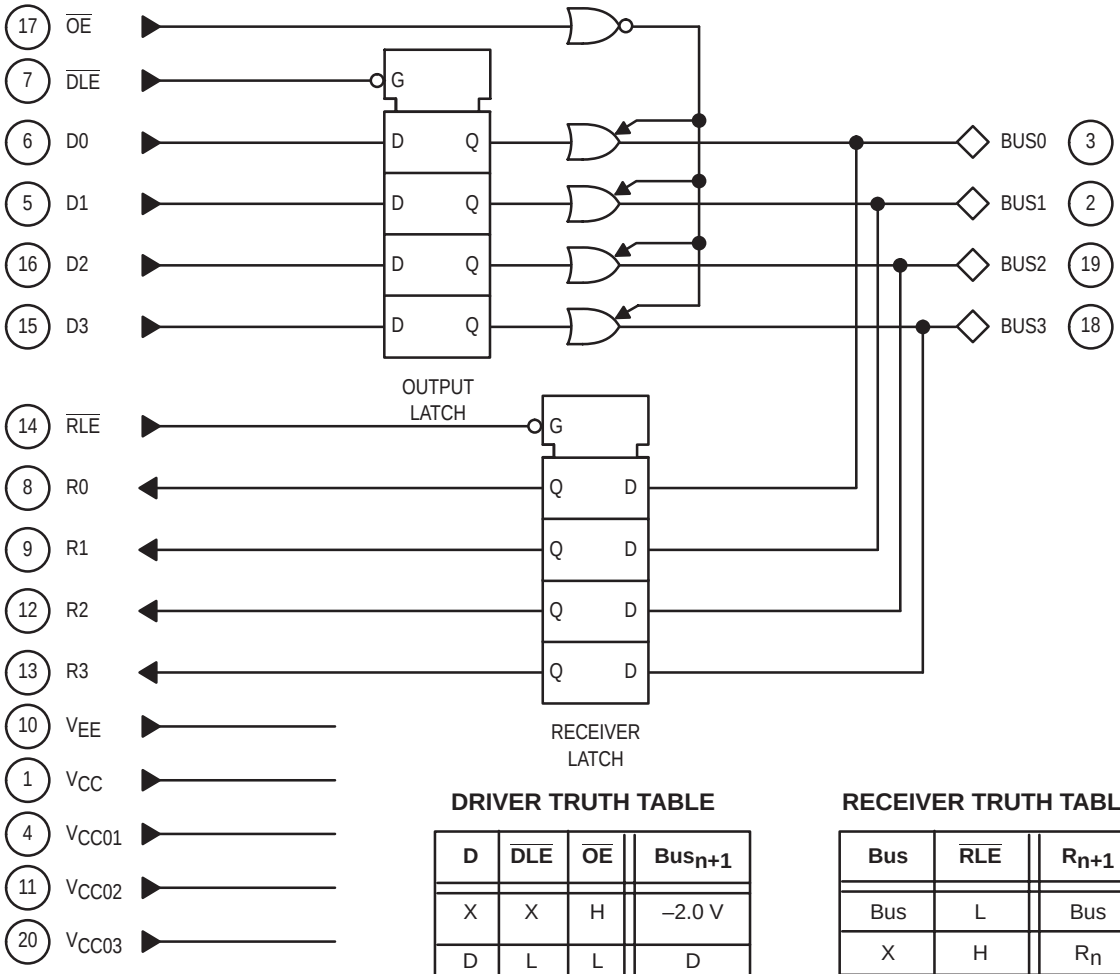
ELECTRICAL CHARACTERISTICS (V_{EE} = –5.2 V ±5%) (See Note)

		0°		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
I_E	Power Supply Current	–	161	–	161	–	161	mA
I_{inH}	Input Current High							µA
	Pins 5,6,15,16	–	397	–	273	–	273	
	Pins 7,14	–	460	–	297	–	297	
	Pin 17	–	520	–	357	–	357	
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	µA
V_{OH}	High Output Voltage	–1.02	–0.84	–0.98	–0.81	–0.92	–0.735	Vdc
V_{OL}	Low Output Voltage	–1.95	–1.63	–1.95	–1.63	–1.95	–1.60	Vdc
V_{IH}	High Input Voltage	–1.17	–0.84	–1.13	–0.81	–1.07	–0.735	Vdc
V_{IL}	Low Input Voltage	–1.95	–1.48	–1.95	–1.48	–1.95	–1.45	Vdc

AC PARAMETERS

t_{pd}	Propagation Delay							ns
	Data–to–Bus Output	0.5	2.5	0.5	2.5	0.5	2.5	
	$\overline{DLE}$–to–Bus Output	1.0	2.7	1.0	2.7	1.0	2.7	
	$\overline{OE}$–to–Bus Output	0.5	2.5	0.5	2.5	0.5	2.5	
	Bus–to–R0	0.5	1.9	0.5	1.9	0.5	1.9	
	$\overline{RLE}$–to–R0	0.5	2.1	0.5	2.1	0.5	2.1	
	Data–to–Receiver R0	1.0	3.8	1.0	3.8	1.0	3.8	
t_r	Rise Time	0.5	2.2	0.5	2.2	0.5	2.2	ns
t_f	Fall Time	0.5	2.2	0.5	2.2	0.5	2.2	ns

LOGIC DIAGRAM



DRIVER TRUTH TABLE

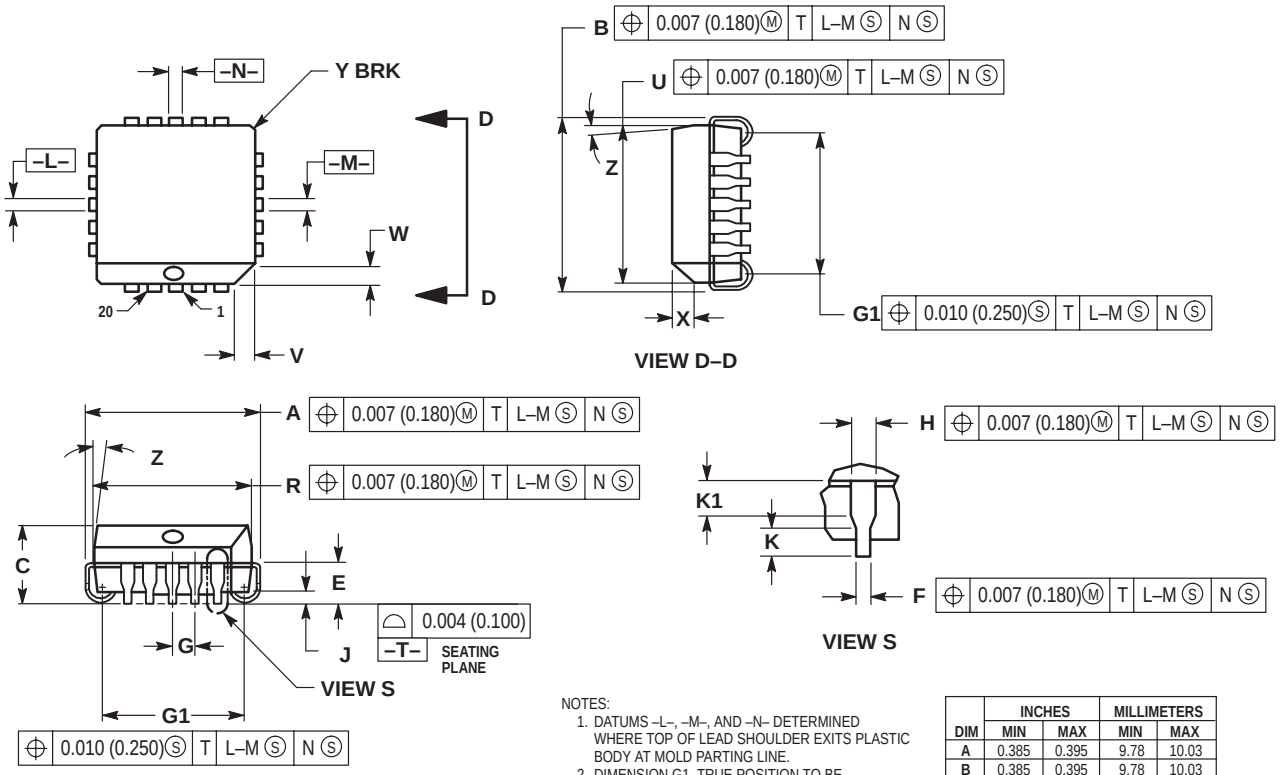
D	$\overline{DLE}$	$\overline{OE}$	Bus_{n+1}
X	X	H	–2.0 V
D	L	L	D
X	H	L	Bus_n

RECEIVER TRUTH TABLE

Bus	$\overline{RLE}$	R_{n+1}
Bus	L	Bus
X	H	R_n

PACKAGE DIMENSIONS

PLCC–20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775–02
ISSUE C

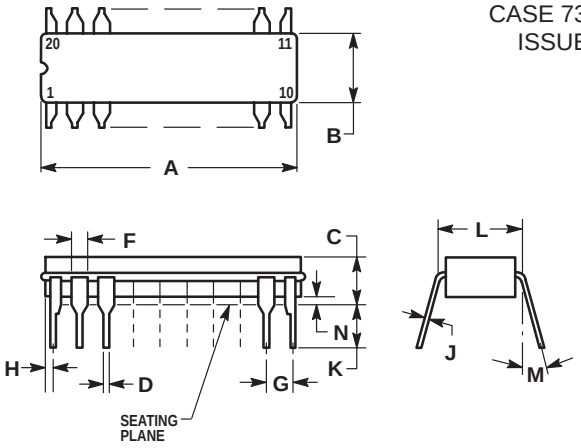


NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	—	1.02	—

PACKAGE DIMENSIONS

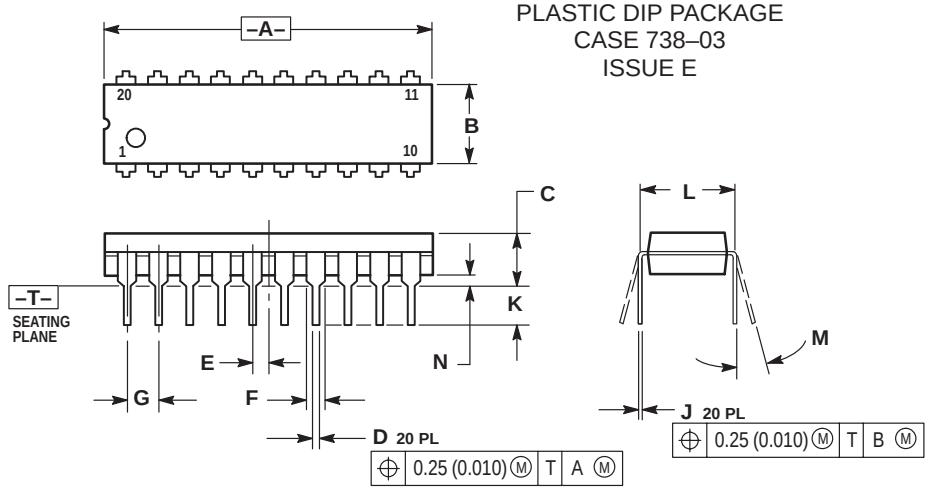
CDIP–20
L SUFFIX
CERAMIC DIP PACKAGE
CASE 732–03
ISSUE E



NOTES:
1. LEADS WITHIN 0.010 DIAMETER, TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSIONS A AND B INCLUDE MENISCUS.

	INCHES	
DIM	MIN	MAX
A	0.940	0.990
B	0.260	0.295
C	0.150	0.200
D	0.015	0.022
F	0.055	0.065
G	0.100 BSC	
H	0.020	0.050
J	0.008	0.012
K	0.125	0.160
L	0.300 BSC	
M	0°	15°
N	0.010	0.040

PDIP–20
P SUFFIX
PLASTIC DIP PACKAGE
CASE 738–03
ISSUE E



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

Notes

Notes

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